

Upcoming: June 1–4, E-MRS Spring Meeting, E-MRS; June 13–18, 5th IUMRS-ICAM'99, IUMRS, MRS-I; June 27–30 ISTE/C/MRS Intl. Workshop on Superconductivity, MRS.

To list an event in the Calendar, contact J. Meiksin, Materials Research Society, 506 Keystone Drive, Warrendale, PA 15086-7573; 724-779-3004 ext. 522; fax 724-779-8313.

MRS, A-MRS, C-MRS, E-MRS, MRS-A, MRS-I, MRS-J, MRS-K, MRS-R, MRS-T, M-MRS, or IUMRS at the end of an entry indicates sponsorship or co-sponsorship of an event by the International Union of Materials Research Societies or one of its adhering bodies. "Endorsed" identifies events endorsed by MRS.

▼ identifies a new or revised entry this month.

See the March 1999 MRS BULLETIN for May 1999 Calendar entries.

JUNE 1999

1–4 43rd Intl. Conf. on Electron, Ion, and Photon Beam Technology and Nanofabrication, *Marco Island, FL*. Mark Gesley Etec Systems, 26460 Corporate Ave., Hayward, CA 94545; 510-887-3312; fax 510-7876-9438; e-mail gesley@etec.com; <http://www.eecs.umich.edu/~pang>.

1–4 E-MRS Spring Meeting, *Strasbourg, France*. E-MRS, B.P. 20, 67037 Strasbourg Cedex 2, France; 33-3-8810-6343; e-mail emrs@phase.c-strasbourg.fr; <http://www.emrs.c-strasbourg.fr>. **E-MRS.**

6–10 12th Intl. Colloquium on Plasma Processes, *Antibes - Juan-les-Pins, France*. SFV, 19 rue du Renard, F-75004, Paris, France; e-mail sfv@club-internet.fr.

7–9 2nd ISOPE European Offshore Mechanics Symposium: Intl. Pipeline Symposium, *Moscow, Russia*. Intl. Society of Offshore and Polar Engineers, P.O. Box 1107, Golden, CO 80402-1107; 303-420-8114; fax 303-420-3760.

7–9 ▼ 12th Annual European Microelectronics Conf., *Yorkshire, England*. Intl. Microelectronics and Packaging Society, 1850 Centennial Park Dr., Ste. 105, Reston, VA 20191-1517; 703-758-1060; fax 703-758-1066; e-mail IMAPS@aol.com; www.imaps.org.

7–10 2nd Worldwide Aerospace Conf., *Long Beach, CA*. D. Baker, Conf. Coordinator, The MacNeal-Schwendler Corp., 815 Colorado Blvd., Los Angeles, CA 90041-1777; 323-259-3862; fax 323-259-4969; www.macsch.com/aerospace.

7–10 10th Intl. Conf. on Solid-State Sensors and Actuators, *Sendai, Japan*. Transducers '99, J. Echizen, 103, Honcho 2-41-16, Nakano-ku, Tokyo 164-0012, Japan; 81-3-3299-1371; fax 81-3-3299-1361; e-mail tr99@twics.com; <http://www.com.cas.uec.ac.jp/trans99.html>.

8–12 7th Intl. Conf. on Fatigue, *Beijing, China*. X.Y. Huang, Beijing Inst. of Aeronautical Materials, P.O. Box 81-23, Beijing 100095, P.R. China; 86-10-62458125; fax 86-10-62456925; e-mail mechbiam@public3.bta.net.cn. **C-MRS.**

9 Composites: From Nano to Macro, *Storrs, CT*. Y.H. Chudy, Institute of Materials Science, University of Connecticut, Storrs, CT 06269-3136; 860-486-3582; fax 860-486-4745; e-mail ychudy@mail.ims.uconn.edu.

9–11 Intl. Conf. on Hot Isostatic Pressing, *Beijing, China*. HIP'99, H. Jingyong, Chinese Materials Research Society, No. 7 Baishiqiao Rd., Beijing 100081, China; phone/fax 86-10-68428640; e-mail cmrsec@public.bta.net.cn. **C-MRS.**

9–11 OSA Topical Meeting on Optical Amplifiers and Their Applications, *Nara City, Japan*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; <http://www.osa.org/mtg-conf>.

10–11 ▼ IEEE Electron Devices Conf., *Madrid, Spain*. Inst. de Física Aplicada, Serrano 144, 28006 Madrid, Spain; 34-91-561-8806; fax 34-91-411-7651; <http://www.ifa.csic.es/cde99/cde99.htm>.

13–18 5th IUMRS-ICAM'99, *Beijing, China*. Secretariat, IUMRS-ICAM-1999, C-MRS Office, 7 Baishiqiao Road, Beijing, 100081, China; 86-10-68428640; fax 86-10-68428640; http://www.chimeb.edu.cn/meeting/e_mrs99.htm. **IUMRS, MRS-I.**

14–16 Intl. Conf. on Metal Foams and Porous Metal Structures, *Bremen, Germany*. A. Böker, Conf. Secretariat, Fraunhofer Inst., Lesumer Heerstr. 36, D-28717 Bremen, Germany; 49-421-6383-211; fax 49-421-6383-190; e-mail bk@ifam.fhg.de; <http://www.ifam.fhg.de/fhg/ifam/metfoam99.html>.

14–17 Surface Analysis Conf., *Waukesha, WI*. T. Barr, Dept. of Materials, Univ. of Wisconsin, Milwaukee, WI 53201; 414-229-4085; fax 414-229-6958; e-mail terybarr@csl.uwm.edu; <http://www.vacuum.org/assd/surf99.html>.

15–17 ▼ Intl. Conf. on Precision Grinding, *Chicago, IL*. Gorham Advanced Materials Inst., P.O. Box 250, Gorham, ME 04038; 207-892-5455; fax 207-892-2210; e-mail gorham@goradv.com.

16–18 5th Intl. Symposium on Sputtering and Plasma Processes, *Kanazawa, Japan*. S. Daikuhara, ISSP'99 Committee Chair, SHIN-CRON Co., Ltd.; 81-3-3762-7812; fax 81-3-3762-8075; e-mail s051daikuhara@shincron.co.jp.

20–23 MCM Applications Conf., *Newport, RI*. Intl. Microelectronics and Packaging Society, 1850 Centennial Park Dr., Ste. 105, Reston, VA 20191-1517; 703-758-1060; fax 703-758-1066; e-mail imaps@imaps.org; www.imaps.org.

20–24 Intl. Conf. on Powder Metallurgy and Particulate Materials, *Vancouver, Canada*. Metal Powder Industries Federation, 105 College Rd. East, Princeton, NJ 08540-6692; 609-452-7700; fax 609-987-8523; www.mpif.org.

21–23 ▼ Microelectronics Marketing Research Council Workshop on Future Communication Networks—Trends and Tradeoffs, *Baltimore, MD*. Intl. Microelectronics and Packaging Society, 1850 Centennial Park Dr., Ste. 105, Reston, VA 20191-1517; 703-758-1060; fax 703-758-1066; e-mail IMAPS@aol.com; www.imaps.org.

21–24 4th Intl. Airborne Remote Sensing Conf., *Ottawa, Ontario, Canada*. ERIM Airborne Conf., Box 134008, Ann Arbor, MI 48113-4008; 734-994-1200, ext. 3234; fax 734-994-5123; e-mail wallman@erim-int.com; <http://www.erim-int.com/conf/conf.html>.

21–24 OSA Topical Meeting on Optical Remote Sensing of the Atmosphere, with the OSA Topical Meeting on Fourier Transform Spectroscopy: New Methods and Applications, *Santa Barbara, CA*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; <http://www.osa.org/mtg-conf>.

21–25 5th Intl. Conf. on Electrical Transport and Optical Properties of Inhomogeneous Media, *Hong Kong, Conf.*. Secretariat, ETOPI5, c/o H. Lai, Dept. of Physics, The Hong Kong Univ. of Science and Technology, Clear Water Bay, Kowloon, Hong Kong; 852-2358-7500; fax 852-2358-1652; e-mail etopim@uicmail.ust.hk; <http://physics.ust.hk/etopim5>.

23–25 ▼ 5th Intl. Workshop on Stress-Induced Phenomena in Metallization, *Stuttgart, Germany*. Dr. Oliver Kraft, Max-Planck-Institut für Metallforschung, Seestr. 92, D-70174 Stuttgart, Germany; 49-711-2095-123; fax 49-711-2095-120; e-mail oliver.kraft@po.uni-stuttgart.de.

23–25 21st Annual Intl. Conf. on the Degradation and Stabilization of Polymers, *Interlaken, Switzerland*. A.V. Patsis, Inst. of Materials Science, State Univ. of New York at New Paltz, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail icinquiry@ims-np.org; <http://www.ims-np.org/interDeg>.

27–30 ISTE/C/MRS Intl. Workshop on Superconductivity, *Kauai, HI*. T. Kobayashi, Secretariat, Intl. Superconductivity Technology Center, Eishin Kaihatsu Bldg. 6F, 34-3, Shimbashi 5-chome, Minato-ku, Tokyo 105-0004, Japan; 81-3-3431-4002; fax 81-3-3431-4044; e-mail t-kobayashi@istec.or.jp. **MRS.**

27–30 OSA Topical Meeting on Applications of High Field and Short Wavelength Sources VIII, *Potsdam, Germany*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; <http://www.osa.org/mtg-conf>.

27–2 Intl. Conf. on Mechanical Properties of Films, Coatings, and Interfacial Materials, *Il Ciocco (Barga), Italy*. Engineering Foundation Conf., 3 Park Ave., 27th Floor, New York, NY 10016; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; <http://www.engfnd.org>.

27–2 Shock Compression of Condensed Matter, *Snowbird, UT*. Meetings Dept., American Physical Society, One Physics Ellipse, College Park, MD 20740-3844; 301-209-3286; <http://www.aps.org>.

30–2 41st Electronic Materials Conf., *Santa Barbara, CA*. Customer Service Dept., TMS, 420 Commonwealth Dr., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail csc@tms.org; <http://www.tms.org>.

JULY 1999

3–7 4th Liquid Matter Conf., *Granada, Spain*. R. Hidalgo Alvarez, Dept. Física Aplicada, Facultad de Ciencias, Univ. de Granada, Campus de Fuentenueva, E-18071 Granada, Spain; 34-958-243-213; fax 34-958-243-214; e-mail liquid99@ugr.es; <http://www.ugr.es/~liquid99>.

5–9 3rd Intl. Conf. on Nitride Semiconductors, *Montpellier, France*. P. Lefebvre, Secretary ICNS3, Univ. de Montpellier II, Groupe d'Etude des Semiconducteurs, Case Courrier 074, 34095 Montpellier Cedex 5, France; 33-0-4-67-14-37-56; fax 33-0-4-67-14-37-60; e-mail lefebvre@ges.univ-montp2.fr.

5–9 25th Annual Intl. Conf. on Organic Coatings: Waterborne, High Solids, and Powdered Coatings, *Athens, Greece*. A.V. Patsis, Inst. of Materials Science, State Univ. of New York at New Paltz, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail icinquiry@ims-np.org; <http://www.ims-np.org/interOrg>.

6–9 Intl. Workshop on Adaptive Optics for Industry and Medicine, *Durham, England*. G.D. Love, Univ. of Durham, Dept. of Physics, Science Laboratories, South Rd., Durham DH1 3LE, UK; 44-191-374-7496; 44-191-374-3709; e-mail g.d.love@durham.ac.uk.

7–9 59th Annual Physical Electronics Conf., *Berkeley, CA*. K. Copp, PEC Conf. Secretariat, L-356, Lawrence Livermore Natl. Lab., 7000 East Ave., P.O. Box 808, Livermore, CA 94550; 925-424-2597; fax 925-424-4737; e-mail copp@llnl.gov; <http://www.physicalelectronics.org>.

8-10 ▼ SEMI Semiconductor Processing Technology Conf., *San Francisco, CA*. J. Sullivan, SEMI North America, 805 E. Middlefield Rd., Mountain View, CA 94043-4080; 650-964-5111; fax 650-967-5375; e-mail jsullivan@semi.org; http://www.semi.org.

11-16 ▼ 2nd Gordon Research Conf. of Materials Processes Far from Equilibrium, *Plymouth, NH*. T. Diaz de la Rubia, Chemistry and Materials Science Directorate, Mail Stop L-353, Lawrence Livermore National Lab., 700 East Ave., Livermore, CA 94550; 925-422-6714; fax 925-422-7300; e-mail delarubia@llnl.gov; http://www.grc.uri.edu/apply.htm.

11-16 Ultrafast Optics Meeting, *Ascona, Switzerland*. U. Keller, Swiss Federal Inst. of Technology Zurich, Inst. of Quantum Electronics, ETH Honggerberg HPT, CH-8093 Zurich, Switzerland; 41-1-633-2146; fax 41-2-633-1059; e-mail keller@iqe.phys.ethz.ch.

12 FEG Electron Microscopy Meeting, *Oxford, UK*. Royal Microscopical Society, 37/38 St. Clements, Oxford OX4 1AJ, UK; 44-1865-248768; fax 44-1865-791237; e-mail meetings@rms.org.uk; http://www.rms.org.uk.

12 ▼ SEMI Chemical Vapor Deposition Technology Conf., *San Francisco, CA*. J. Sullivan, SEMI North America, 805 E. Middlefield Rd., Mountain View, CA 94043-4080; 650-964-5111; fax 650-967-5375; e-mail jsullivan@semi.org; http://www.semi.org.

12-14 Intl. Conf. on Aging Studies and Lifetime Extension of Materials, *Oxford, United Kingdom*. L.G. Mallinson, AWE Aldermaston, Reading RG7 4PR, U.K.; 44 (0)118 9827993; fax 44 (0)118 9824739; e-mail lmallinson@awe.co.uk.

12-14 SEMICON/West 99: *Water Processing, San Francisco, CA*. J. Sullivan, SEMI North America, 805 E. Middlefield Rd., Mountain View, CA 94043-4080; 650-964-5111; fax 650-967-5375; e-mail jsullivan@semi.org; http://www.semi.org.

12-16 Cryogenic Engineering Conf., and Intl. Cryogenic Materials Conf., *Montreal, Quebec, Canada*. Centennial Conferences, 303-499-2299; fax 303-499-2599; e-mail centennial@orci.com; http://www.cec-icmc.org.

14-16 7th Microoptics Conf., *Makuhari Messe, Chiba, Japan*. Y. Koike, Keio Univ., 3-14-1 Hiyoshi, Kohoku-ku, Yokohama 223-0061, Japan; 81-1-45-563-1141; fax 81-45-562-7373; e-mail y-koike@inst.keio.ac.jp; http://www.din.or.jp/microopt/mocpof99.html.

14-16 SEMICON/West 99; Test, Assembly and Packaging, *San Jose, CA*. J. Sullivan, SEMI North America, 805 E. Middlefield Rd., Mountain View, CA 94043-4080; 650-964-5111; fax 650-967-5375; e-mail jsullivan@semi.org; http://www.semi.org.

15-17 Conf. on Next Generation Packaging, *Solvang, CA*. Intl. Microelectronics and Packaging Society, 1850 Centennial Park Dr., Ste. 105, Reston, VA 20191-1517; 703-758-1060; fax 703-758-1066; e-mail imaps@imaps.org; www.imaps.org.

18-23 SPIE Annual Meeting and Optical Instrumentation Show, *Denver, CO*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; http://www.spie.org.

19-23 ▼ 3rd Intl. Conf. on Solvothermal Reactions, *Bordeaux, France*. G. Demazeau, Chairman, IHP-ENSCP, B. P. 108, 33402 Talence Cedex, France; 33-5-5684-2749; fax 33-5-5684-2710; e-mail demazeau@chimsol.icmcb.u-bordeaux.fr; http://www.enscpb.u-bordeaux.fr/icstr-3.

19-23 COLA'99: 5th Intl. Conf. on Laser Ablation, *Goettingen, Germany*. Dr. Michael Stuke, Max-Planck-Institut für Biophysikalische Chemie, PO Box 2841, D-37018 Goettingen, Germany; 49-551-201-1338 or 1314; fax 49-551-201-1330 or 1530; e-mail mstuke@gwdg.de.

19-23 OSA Topical Meetings on Integrated Photonics Research; Photonics in Switching; and Advanced Semiconductor Lasers and Their Applications, *Santa Barbara, CA*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; http://www.osa.org/mtg-conf.

19-23 Radiation Effects in Insulators, *Jena, Thuringia, Germany*. REI-10, c/o U. Bornkessel, Friedrich-Schiller-Univ. Jena, Inst. für Festkörperphysik, Max-Wien-Platz 1, D-07743 Jena, Germany; 49-3641-947315; fax 49-3641-947302; e-mail bornkessel@pinet.uni-jena.de; http://www.physik.uni-jena.de/~exphys/rei10/.

25-30 14th Intl. Conf. on the Chemistry of the Organic Solid State, *Cambridge, England*. ICCOSS XIV, W. Jones, Univ. of Cambridge, Dept. of Chemistry, Lensfield Rd., Cambridge CB1 2EW, United Kingdom; 44-1223-336468; fax 44-1223-336362; e-mail ICCOSSXIV@ch.cam.ac.uk.

25-30 26th Annual Review of Progress in Quantitative Nondestructive Evaluation, *Montreal, Quebec, Canada*. E-mail qnde3@cnde.iastate.edu; www.cnde.iastate.edu/qnde/qnde.html.

26-30 6th Intl. Conf. on the Structure of Surfaces, *Vancouver, Canada*. K.A.R. Mitchell, Dept. of Chemistry, Univ. of British Columbia, Vancouver, BC, Canada V6T 1Z1; 604-822-3266; fax 604-822-2847.

26-30 20th Intl. Conf. on Defects in Semiconductors, *Berkeley, CA*. ICDS-20, M/S 2-200, Berkeley Lab., Univ. of California, Berkeley, CA 94720; e-mail icds-20@lbl.gov; http://www.lbl.gov/msd/ICDS-20.

26-30 ICO Satellite Meeting on Light for Life, and Education and Training on Optics and Photonics Conf., *Cancun, Mexico*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; http://www.spie.org.

28-30 Education and Training on Optics and Photonics Conf., *Cancun, Mexico*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; http://www.spie.org.

AUGUST 1999

1-5 9th Intl. Conf. on Environmental Degradation of Materials in Nuclear Power Systems—Water Reactors, *Newport Beach, CA*. TMS Customer Service Dept., 420 Commonwealth Dr., Warrendale, PA 15086-7514; 724-776-9000; fax 724-776-3770; e-mail csc@tms.org; http://www.tms.org/meetings/meetings.html.

1-6 11th Conf. on Crystal Growth and Epitaxy, *Tucson, AZ*. T. Gentile, ACCGE-11 Secretariat, American Assoc. for Crystal Growth, P.O. Box 3233, Thousand Oaks, CA 91359-0233; 805-492-7047; fax 805-492-4062; e-mail aacg@lafn.org; http://www.aaml.arizona.edu/aacg.

2-6 Denver X-ray Conf., *Steamboat Springs, CO*. D. Flaherty, Conf. Coordinator, ICDD, 12 Campus Blvd., Newtown Square, PA 19073-3273; 610-325-9814; fax 610-325-9823; e-mail flaherty@icdd.com; http://www.dxcidd.com.

4-13 18th Intl. Union of Crystallography Congress, *Glasgow, Scotland, UK*. Northern Networking Ltd., Congress Central Office, Bellway House, 813 South Street, Glasgow G14 0BX, Scotland, UK; 44-141-954-4441; fax 44-141-954-2656; e-mail crystal@glasconf.demon.co.uk; http://www.chem.gla.ac.uk/iucr99.

8-13 ▼ 2nd Intl. Alloy Conf., *Davos, Switzerland*. Engineering Foundation Conferences, Three Park Ave., 27th Floor, New York, NY 10016; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; http://www.uefoundation.org.

9-11 ▼ Intl. Workshop on Dense Gas Dynamics, *Boulder, CO*. Inst. for Advanced Physics, 10875 U.S. Hwy. 285, Ste. 199, Conifer, CO 80433; e-mail dgd99@IAPhysics.org; http://www.IAPhysics.org/conferences/dgd99/.

9-13 12th Intl. Conf. on Textures of Materials, *Montreal, Quebec, Canada*. J.A. Szpunar, ICOTOM 12, Dept. of Metallurgical Engineering, McGill Univ., 3610 University St., Montreal, PQ, Canada, H3A 2B2.

15-20 2nd Conf. on Thermal Spray Processing of Nanoscale Materials, *Quebec City, Canada*. United Engineering Foundation, Three Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; http://www.engfund.org.

22-26 Fall Natl. ACS Meeting, *New Orleans, LA*. Div. of Meetings, American Chemical Society, 1155 16th St. N.W., Washington, DC 20036; 202-872-4396; fax 202-872-6128; e-mail natlmtgs@acs.org; http://www.acs.org.

22-27 ▼ 18th Intl. Conf. on Amorphous and Microcrystalline Semiconductors, *Snowbird, UT*. ICAMS18, Univ. of Utah, Dept. of Physics, 115 S. 1499 E. Rm. 201, Salt Lake City, UT 84112-0830; 801-581-4246; fax 801-581-4801; ICAMS18@mail.physics.utah.edu; http://icams18.physics.utah.edu.

23-27 10th Intl. Conf. on Rapidly Quenched and Metastable Materials, *Bangalore, India*. S. Ranganathan and K. Chattopadhyay, Dept. of Metallurgy, Indian Inst. of Science, Bangalore 560012, India; 91-80-309-2678; fax 91-80-331-2991; e-mail rqtan@metallrg.iisc.ernet.in; http://www.metallrg.iisc.ernet.in/~rqtan.

23-27 18th Intl. Conf. on X-Ray and Inner-Shell Processes, *Chicago, IL*. X-99 Conf. Office, Physics Div., Argonne Natl. Lab., Bldg. 203, Rm. G-122, 9700 S. Cass Ave., Argonne, IL 60439-4843; 630-252-4044; fax 630-252-2864; e-mail x99@anl.gov; http://www.phy.anl.gov/x99.

27-29 1st Intl. Conf. on Scanning Probe Microscopy of Polymers, *Santa Barbara, CA*. T. Mehr, Conf. Coordinator, 112 Robin Hill Rd., Santa Barbara, CA 93117; 805-967-1401; e-mail terry@di.com; www.di.com/poly/poly.html.

30-3 11th Intl. Conf. on Thin Films, *Cancun, Mexico*. ICTF-11/SMCSVC-19, Dept. de Fisica, Centro de Investigacion y de Estudios Avanzados del I.P.N.P.O., Box 14-740, Mexico 07000 D.F., Mexico; 52-5-7477000; fax 52-5-7477096; e-mail ictf99@fis.cinvestav.mx.

30-3 Conf. on Lasers and Electro-Optics/Pacific Rim, *Seoul, Korea*. Optical Society of Korea, Rm. 811, Korea Science & Technology Ctr., 635-4, Yucksam-dong, Kangnam-ku, Seoul 135-703, Korea; 82-2-3452-6560; fax 82-2-3452-6561.

SEPTEMBER 1999

1-3 OSA Topical Meeting on Nonlinear Guided Waves and Their Applications, *Dijon, France*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; http://www.osa.org/mtg-conf.

1-4 Surfaces in Biomaterials Conf., *Scottsdale, AZ*. Surfaces in Biomaterials Foundation, 13355 10th Ave. N., Minneapolis, MN 55441; 612-915-1011; fax 612-927-8127; http://www.surfaces.org.

2-4 ▼ 15th Annual Meeting of the Academy of Surgical Research, *Scottsdale, AZ*. The Academy of Surgical Research, 13355 10th Ave. North, Ste. 108, Minneapolis, MN 55441-5510; 612-545-1919; fax 612-545-0335; http://www.surgicalresearch.org.

2-8 6th Intl. Conf. on Hydrogen Materials Science and Chemistry of Metal Hydrides, *Katsiveli, Yalta, Ukraine*. D.V. Schur, S. Yu Zaginachenko, Program Committee ICHMS'99, P.O. Box 195, Kiev-150, 252150, Ukraine; phone/fax 380-44-444-0001; e-mail shurzag@ipms.kiev.ua.

5-7 ICSSS—International Conference on Solid State Spectroscopy, *Schwäbisch Gmünd, Germany*. Sabine Birtel, fax 49-711-689-1712; e-mail icssss@cardix.mpi-stuttgart.mpg.de; http://cardix.mpi-stuttgart.mpg.de/icssss/.

5-9 15th European Conf. on Thermophysical Properties, Würzburg, Germany. J. Fricke, ZAE Bayern, Am Hubland, D-97074 Würzburg, Germany; e-mail ectp@zae.uni-wuerzburg.de; http://www.zae-bayern.de/ectp.

5-9 Extraction and Process Metallurgy Conf., and World Congress on Recycling Waste Treatment and Minimization of Wastes, San Sebastian, Spain. Customer Service Dept., TMS, 420 Commonwealth Dr., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail csc@tms.org; http://www.tms.org.

6-8 6th Intl. Conf. on Interfacial Phenomena in Composite Materials, Berlin, Germany. A. Hampe, BAM, Berlin, Germany; 49-30-8104-1600; fax 49-30-8104-1607; e-mail andreas.hampe@bam.de.

6-9 3rd Intl. Conf. on Shape Memory and Superelastic Technologies, Antwerp, Belgium. SMST-99, vzw, Kroonstraat 4, B-3210 Lubbeek, Belgium; 32-1355-3513; fax 32-1355-3514.

6-9 Euro-Fillers '99 Conf., Lyon-Villeurbanne, France. Euro-Fillers '99 Secretariat, Lab. des Matériaux, Macromoléculaires, Inst. Natl. des Sciences Appliquées, Bât. 403-20, Ave. Albert Einstein, 69621 Villeurbanne Cedex, France; 33-4-7243-8979; fax 33-4-7243-8527; e-mail eurofillers@insa-lyon.fr.

6-10 8th Intl. Conf. on Ion Sources, Kyoto, Japan. J. Ishikawa, Electronic Science and Engineering Dept., Kyoto Univ., Yoshida-hommachi, Sakyo-ku, Kyoto 606-8501, Japan; 81-75-753-5325; fax 81-75-753-5324; e-mail icis99@mvtpc3.kuee.kyoto-u.ac; http://mvtpc3.kuee.kyoto-u.ac.jp/icis99.

10-15 10th Intl. Conf. on Recent Progress in Many-Body Theories, Seattle, WA. A. Bulgac, Dept. of Physics, Univ. of Washington, P.O. Box 351560, Seattle, WA 98195-1560; fax 206-685-9829; e-mail mbx@phy.washington.edu; http://www.phys.washington.edu/~mbx.

12-16 4th Intl. Conf. on Nuclear Physics at Storage Rings, Bloomington, IN. J. Meadows, Indiana Univ. Cyclotron Facility, 2401 Milo B. Sampson Lane, Bloomington, IN 47408; 812-855-9365; 812-855-6645; e-mail stori99@iucf.indiana.edu.

13-15 4th Intl. Conf. on Spray Forming, Baltimore, MD. J. Abrahams, Conf. Secretariat, "Beggars Roost," Channels End Rd., Colmworth, Bedfordshire MK44 2NS, UK; 44-12-34-37-8862; fax 44-12-34-37-6219; e-mail 100700.2023@compuserve.com.

13-16 SEMI Chip Scale Intl. Conf., San Jose, CA. J. Sullivan, SEMI North America, 805 E. Middlefield Rd., Mountain View, CA 94043-4080; 650-964-5111; fax 650-967-5375; e-mail jsullivan@semiorg; http://www.semi.org.

13-17 7th Intl. Conf. on Microwave and High Frequency Heating, Valencia, Spain. 7th Intl. Conf. Microwave & HF Heating, TOT NOU, C/Cirilo Amorós, 27-2°-C, E-46004 Valencia, Spain; 34-96-394-3445; fax 34-96-394-1654; e-mail microwav@etsit.upv.es; http://www.digital.es/icom/totnou.

19-23 Specialty Conf. on Copper, Phoenix, AZ. Customer Service Dept., TMS, 420 Commonwealth Dr., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail csc@tms.org; http://www.tms.org.

20-24 3rd Conf. of the Yugoslav Materials Research Society, Herceg Novi, Yugoslavia. Yu-MRS Conf. Secretariat, Inst. of Technical Sciences of the Serbian Academy of Sciences and Arts, Knez Mihailova 35/IV, P.O. Box 745, 11000 Belgrade, Yugoslavia; 381-11-185-437; fax 381-11-185-263; e-mail yumrs@itn.sanu.ac.yu; http://www.yu-mrs.org.yu.

21-23 1st Intl. SAMPE Automotive Conf., Meeting of the Engineering Society, and the Engineering Society/Society of Automotive Engineers Intl. Body Engineering Conf., Detroit, MI. C.L. Hammermesh, Technical Director, Society for Advancement of Material and Process Engineering, SAMPE Intl. Business Office, P.O. Box 2459, Covina, CA 91722-8459; 626-331-0616; fax 626-332-8929.

21-24 18th European Conf. on Surface Science, Vienna, Austria. ECOS-18 Secretary, Inst. für Allgemeine Physik, TU-Wien, Wiedner Hauptstr. 8-10/E134, A-1040 Vienna, Austria.

22-24 SPIE Intl. Symposium on Microelectronic Manufacturing, Santa Clara, CA. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; http://www.spie.org/info/mm.

24-26 OSA/ACS Topical Meeting on Organic Thin Films for Photonics Applications; with OSA Topical Meeting on Bragg Coatings, Photosensitivity, and Poling in Glass Waveguides; Santa Clara, CA. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; http://www.osa.org/mtg-conf.

26-1 OSA Annual Meeting, and Interdisciplinary Laser Science Conf., Santa Clara, CA. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; http://www.osa.org/mtg-conf.

27-29 1st Intl. SAMPE Automotive Conf., with ESD Advanced Coatings Technology Conf., Detroit, MI. Society for the Advancement of Material and Process Engineering, 1161 Parkview Dr., Covina, CA 91724-3748; 626-331-0616; fax 626-332-8929; e-mail sampeibo@aol.com; www.et.byu.edu/~sampe.

27-30 European Conf. on Advanced Materials and Processes, Munich, Germany. EUROMAT Congress Office, c/o Deutsche Gesellschaft für Materialkunde, Hamburger Allee 26, D-60486 Frankfurt, Germany; 49-69-7917-750; fax 49-69-7917-733; http://www.fems.org.

28-30 Advanced Metallization Conf., Orlando, FL. Univ. of Calif. Berkeley Extension, 1995 University Ave., Berkeley, CA 94720-7010; 510-642-4151; fax 510-642-6027; e-mail course@unx.berkeley.edu.

OCTOBER 1999

4-7 IEEE Intl. Silicon-on-Insulator Conf., Rohnert Park, CA. BACM, 520 Washington Blvd., Ste. 350, Marina del Rey, CA 90292; 310-305-7885; fax 310-305-1038; e-mail bacm@mediaone.net; http://www.drscdca.com/%7esoiconf-www.drscdca.com/~soiconf.

4-8 8th European Conf. on Applications of Surface and Interface Analysis, Sevilla, Spain. ECASIA99, Dept. Física Aplicada, C-XII, Facultad de Ciencias, Univ. Autónoma de Madrid, Cantoblanco E 28049, Madrid, Spain; fax 34-1-397-3969; e-mail josem.sanz@uam.es; http://www.uam.es/fa/ecasia99.html.

5-8 52nd Annual Gaseous Electronic Conf., Norfolk, VA. L. Vuskovic, Dept. of Physics, 4600 Elkhorn Ave., Rm. 306, Old Dominion Univ., Norfolk, VA 23529; 757-683-4611; fax 757-683-3038; e-mail vuskovic@physics.odu.edu.

10-15 9th Intl. Conf. on Fusion Reactor Materials, Colorado Springs, CO. R.H. Jones, ICFRM-9 General Chairperson, Pacific Northwest National Lab., P.O. Box 999, MSIN P8-15, Richland, WA 99352; 509-376-3701; fax 509-376-0418; e-mail bev.wardlow@pnl.gov.

11-13 8th Intl. Symposium on Semiconductor Manufacturing, Santa Clara, CA. E-mail ISSM@meetingsplus.com; http://www.issm.com.

17-22 196th Meeting of The Electrochemical Society and Fall Meeting of The Electrochemical Society of Japan, Honolulu, HI. The Electrochemical Society, 10 S. Main St., Pennington, NJ 08534-2896; 609-737-1902; fax 609-737-2743; e-mail ecs@electrochem.org; http://www.electrochem.org.

19-20 SEMICON/Southwest, Austin, TX. J. Sullivan, SEMI North America, 805 E. Middlefield Rd., Mountain View, CA 94043-4080; 650-964-5111; fax 650-967-5375; e-mail jsullivan@semiorg; http://www.semi.org.

25-27 2nd Intl. Symposium on Adhesion Measurement of Thin Films and Coatings, Newark, NJ. R.H. Lacombe, Conf. Chairman, 3 Hammer Dr., Hopewell Junction, NY 12533; 914-227-7026; fax 212-656-1016; e-mail rhlacombe@compuserve.com; http://mstconf.com/adhmeas.htm.

25-29 AVS 46th Intl. Symposium, Boston, MA. American Vacuum Society, 120 Wall St., 32nd Floor, New York, NY 10005-3993; 212-248-0200; fax 212-248-0245; e-mail avsnyc@vacuum.org; http://www.vacuum.org.

26-28 32nd Intl. Symposium on Microelectronics, Chicago, IL. Intl. Microelectronics and Packaging Society, 1850 Centennial Park Dr., Ste. 105, Reston, VA 20191-1517; 703-758-1060; fax 703-758-1066; e-mail imaps@imaps.org; www.imaps.org.

26-30 31st Intl. SAMPE Technical Conf., with the Composite Fabricators Association, Chicago, IL. Society for the Advancement of Material and Process Engineering, 1161 Parkview Dr., Covina, CA 91724-3748; 626-331-0616; fax 626-332-8929; e-mail sampeibo@aol.com; www.et.byu.edu/~sampe.

28-29 Intl. Symposium on Adhesion Aspects of Thin Films, Newark, NJ. R.H. Lacombe, Conf. Chairman, 3 Hammer Dr., Hopewell Junction, NY 12533; 914-227-7026; fax 212-656-1016; e-mail rhlacombe@compuserve.com; http://mstconf.com/adhfilm.htm.

31-3 14th Annual National Educators' Workshop, Auburn Hills, MI. J. Jacobs, School of Technology, Norfolk State Univ., 2401 Corprew Ave., Norfolk, VA 23504; 757-683-8109; fax 757-683-8215; e-mail j_jacobs@vger.nsu.edu; http://coulomb.nsu.edu/new.

NOVEMBER 1999

1-3 3rd North American Conf. on the Science and Technology of Emulsion Polymers/Polymer Colloids, Hilton Head Island, SC. Inst. of Materials Science, 75 S. Manheim Blvd., New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail nainquiry@ims-np.org/narcCol.

1-3 Intl. Conf. on the Science, Technology, and Applications of Sintering, State College, PA. R. Cornwall, Materials Research Lab., 277 MRL, Pennsylvania State Univ., University Park, PA 16802; 814-863-8735; fax 814-863-9704; e-mail rgc5@psu.edu; http://www.pmlab.psu.edu/sint99.

1-4 ASM Intl. Materials Solutions Conf., Cincinnati, OH. ASM Intl., Materials Park, OH 44703-0002; 440-338-5151; fax 440-338-4634; www.asm-intl.org.

8-10 3rd ISOPE Ocean Mining Symposium, Goa, India. Intl. Society of Offshore and Polar Engineers, P.O. Box 1107, Golden, CO 80402-1107; 303-420-8114; fax 303-420-3760.

15-18 2nd Intl. Conf. on Processing Materials for Properties, San Francisco, CA. Customer Service Dept., TMS, 420 Commonwealth Dr., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail csc@tms.org; http://www.tms.org.

15-18 18th Intl. Congress on Applications of Lasers and Electro-Optics, San Diego, CA. Laser Inst. of America, 12424 Research Pkwy., Ste. 125, Orlando, FL 32826; 407-380-1553; fax 407-380-5588; e-mail lia@LaserInstitute.org; www.LaserInstitute.org.

29-1 Intl. Symposium on Polyimides and Other High Temperature Polymers: Synthesis, Characterization, and Applications, Newark, NJ. R.H. Lacombe, Conf. Chairman, 3 Hammer Dr., Hopewell Junction, NY 12533; 914-227-7026; fax 212-656-1016; e-mail rhlacombe@compuserve.com; http://mstconf.com/polyimd.htm.

29-3 MRS Fall Meeting, Boston, MA. Materials Research Society, 506 Keystone Drive, Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; http://www.mrs.org/.

DECEMBER 1999

1-3 SEMICON Japan 99, Chiba, Japan. J. Sullivan, SEMI North America, 805 E. Middlefield Rd., Mountain View, CA 94043-4080; 650-964-5111; fax 650-967-5375; e-mail jsullivan@semiorg; http://www.semi.org.

2-3 ▼ 7th Intl. Symposium on Metallized Plastics: Fundamental and Applied Aspects, Newark, NJ. R.H. Lacombe, Conf. Chairman, 3 Hammer Dr., Hopewell Junction, NY 12533; 914-227-7026; fax 212-656-1016; e-mail rhlacombe@compuserve.com; http://mstconf.com/metalpla.htm.

6-8 ▼ IEEE Intl. Electron Devices Meeting, Washington, DC. http://ieeep.org/conference/iedm.

6-8 ▼ Intl. Conf. on Computational Fluid Dynamics in Minerals and Process Industries, Melbourne, Australia. P. Schwarz, CSIRO Minerals, Box 312, Clayton South, Victoria 3169, Australia; 613-9545-8500; fax 613-9562-8919; e-mail cfd@minerals.csiro.au; http://www.minerals.csiro.au.

8 ▼ Greater Southwest Implant Users' Group, San Antonio, TX. J. Arps, 210-522-6588.

FEBRUARY 2000

7-9 2000 IEEE Intl. Solid-State Circuits Conf., San Francisco, CA. D. Suiters; 202-331-2000; e-mail isscc@courtesyassoc.com.

20-24 TMS Annual Meeting, Nashville, TN. Customer Service Dept., TMS, 420 Commonwealth Dr., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail csc@tms.org; http://www.tms.org.

MARCH 2000

5-10 Optical Fiber Communication Conf., Baltimore, MD. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; http://www.osa.org/mtg-conf.

6-8 Polymer Stabilizers and Modifiers Conf., Hilton Head Island, SC. Inst. of Materials Science, 75 S. Manheim Blvd., New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail nainquiry@ims-np.org/narcStab.

20-24 APS 2000 March Meeting, Minneapolis, MN. Meetings Dept., American Physical Society, One Physics Ellipse, College Park, MD 20740-3844; 301-209-3286; http://www.aps.org.

APRIL 2000

2-7 2nd World Congress on Microwave Processing, Orlando, FL. D.E. Clark, Organizing Committee Chair, Dept. of Materials Science and Engineering, 136 MAE, Univ. of Florida, P.O. Box 116400, Gainesville, FL 32611-6400; 352-392-7660; fax 352-846-2033. Endorsed.

3-4 Microscopy of Composite Materials V, Oxford, UK. Royal Microscopical Society, 37/38 St. Clements, Oxford OX4 1AJ, UK; 44-1865-248768; fax 44-1865-791237; e-mail meetings@rms.org.uk; http://www.rms.org.uk.

11-13 Intl. Microscopy Conf., London, UK. Royal Microscopical Society, 37/38 St. Clements, Oxford OX4 1AJ, UK; 44-1865-248768; fax 44-1865-791237; e-mail meetings@rms.org.uk; http://www.rms.org.uk.

16-19 6th Intl. Multi-disciplinary Conf.: Complexity and Fractals in the Sciences, Singapore. http://www.kingston.ac.uk/fractal.

24-28 MRS Spring Meeting, San Francisco, CA. Materials Research Society, 506 Keystone Drive, Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; http://www.mrs.org/. MRS.

MAY 2000

7-12 Conf. on Lasers and Electro-Optics, and Quantum Electronics and Laser Science Conf., San Francisco, CA. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; http://www.osa.org/mtg-conf.

15-20 6th World Biomaterials Congress, Kamuela (Big Island), HI. Society for Biomaterials, 13355 10th Ave. N., Ste. 108, Minneapolis, MN 55441; 612-927-8108; fax 612-927-8127; e-mail biomaterials.org; http://www.biomaterials.org.

22-27 26th Congress on Chemical Engineering, Environmental Protection, and Biotechnology, Frankfurt am Main, Germany. DECHEMA Deutsche Gesellschaft für Chemisches Apparatewesen, Chemische Technik und Biotechnologie e.V., Th. Scheuring, Germany; 49-69-7564-230; fax 49-69-7564-298; http://www.dechema.de.

28-2 10th Intl. Offshore and Polar Engineering Conf., Seattle, WA. Intl. Society of Offshore and Polar Engineers, P.O. Box 1107, Golden, CO 80402-1107; 303-420-8114; fax 303-420-3760.

JULY 2000

17-21 5th Intl. Conf. on Diffusion in Materials, Paris, France. DIMAT 2000, DECM/SRMP, Bat. 520, CEA/SACLAY, 91191 Gif-sur-Yvette Cedex, France; e-mail dimat2000@cea.fr; www.dimat2000.cea.fr.

30-4 SPIE Annual Meeting, San Diego, CA. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; http://www.spie.org.

SEPTEMBER 2000

3-8 Congress of Histochemistry and Cytochemistry, York, UK. Royal Microscopical Society, 37/38 St. Clements, Oxford OX4 1AJ, UK; 44-1865-248768; fax 44-1865-791237; e-mail meetings@rms.org.uk; http://www.rms.org.uk.

10-15 Conf. on Lasers and Electro-Optics/Europe, and Intl. Quantum Electronics Conf., Nice, France. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; http://www.osa.org/mtg-conf.

17-22 13th Intl. Conf. on Ion Implantation Technology, Tyrol, Austria. IIT 2000, c/o IIS-B, Schottkystrasse 10, 91058 Erlangen, Germany; 49-9131-761-100; fax 49-9131-761-102; e-mail iit2000@iis-b.fhg.de; http://www.mfa.kfki.hu/IIT2000.

OCTOBER 2000

2-6 AVS 47th Intl. Symposium, Boston, MA. American Vacuum Society, 120 Wall St., 32nd Floor, New York, NY 10005-3993; 212-248-0200; fax 212-248-0245; e-mail avsnyc@vacuum.org; http://www.vacuum.org.

20-28 OSA Annual Meeting, Providence, RI. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; http://www.osa.org/mtg-conf.

NOVEMBER 2000

13-14 ASTM Symposium on Marine Corrosion in Tropical Environments, Merida, Yucatan, Mexico. V. Chaker, Port Authority of NY-NJ, One World Trade Ctr., 74W, New York, NY 10048; 212-435-5790; fax 215-435-8040.

27-1 MRS Fall Meeting, Boston, MA. Materials Research Society, 506 Keystone Drive, Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; http://www.mrs.org/. MRS. □

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